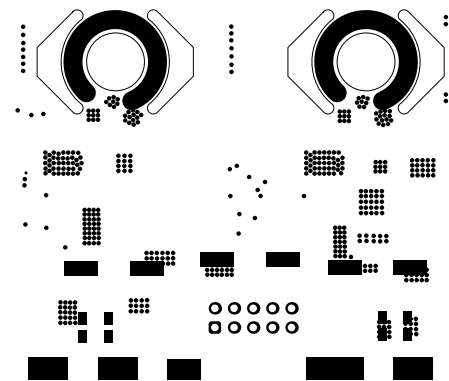
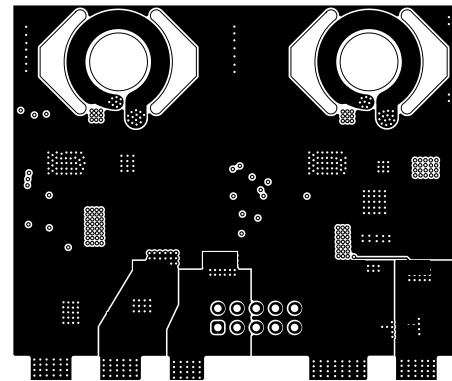


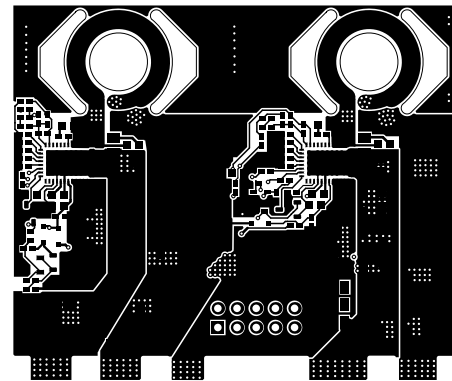
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01444	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: 01444		
PLOT NAME = Top Overlay	GENERATED : 6/22/2017	2:27:52 PM	TEXAS INSTRUMENTS



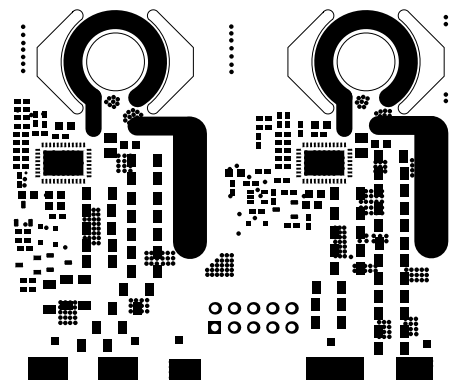
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01444	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: 01444		
PLOT NAME = Top Solder Mask	GENERATED : 6/22/2017 2:27:53 PM	TEXAS INSTRUMENTS	



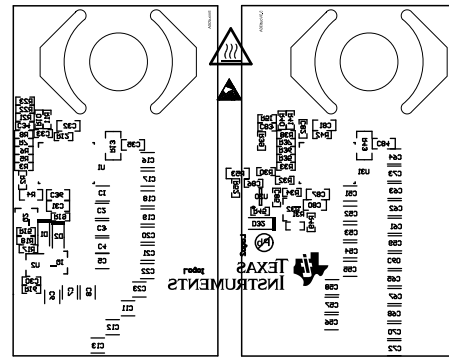
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01444	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: 01444		
PLOT NAME = Top Layer	GENERATED : 6/22/2017 2:27:54 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01444	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: 01444		
PLOT NAME = Bottom Layer	GENERATED : 6/22/2017 2:27:56 PM	TEXAS INSTRUMENTS	

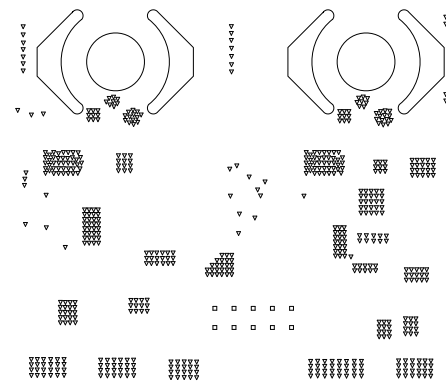


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01444	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: 01444		
PLOT NAME = Bottom Solder Mask	GENERATED : 6/22/2017 2:27:57 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01444	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: 01444		
PLOT NAME = Bottom Overlay	GENERATED : 6/22/2017 2:27:58 PM	TEXAS INSTRUMENTS	

Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
▽	560	11.81mil (0.300mm)	PTH	Round	Top Layer - Bottom Layer	
□	10	39.37mil (1.000mm)	PTH	Round	Top Layer - Bottom Layer	
	570 Total					



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01444	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: 01444		
PLOT NAME = Drill Drawing	GENERATED : 6/22/2017 2:28:00 PM	TEXAS INSTRUMENTS	

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01444	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: 01444		
PLOT NAME = Board Dimensions	GENERATED : 6/22/2017 2:28:01 PM		TEXAS INSTRUMENTS



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